**Layer Deposition**

**Vapor based deposition**

1. **Sputter deposition**

Input: Sample/Substrate, target Material, Gas

Settings: target thickness (nm), pressure (mbar). Capman pressure (mmmHG, mTorr), temperature (°C), burn in time (s), deposition time (s), power (W), voltage (V), gas flow rate (sccm)

Process information:

Output: Layer with functional role

1. **Thermal PVD/Evaporation**

Input: Sample/Substrate, target Material

Settings: thickness (nm), pressure (mbar), start rate (angstrom/s), target rate (angstrom/s), time, temperature (°C), power (W)

Process information:

Output: Layer with functional role

1. **Pulsed laser deposition**

Input: Sample/Substrate, solid Material

Settings:

Process information:

Output: Layer with functional role

1. **Electron-beam-induced deposition**

Input: Sample/Substrate, solid Material

Settings:

Process information:

Output: Layer with functional role

1. **Molecular beam epitaxy**

Input: Sample/Substrate, solid Material

Settings:

Process information:

Output: Layer with functional role

1. **Metal organic chemical vapor deposition**

Input: Sample/Substrate, solid Material

Settings:

Process information:

Output: Layer with functional role

1. **Plasma assisted chemical vapour deposition**

Input: Sample/Substrate, solid Material

Settings:

Process information:

Output: Layer with functional role

1. **Atomic layer deposition**

Input: Sample/Substrate, solid Material

Settings:

Process information:

Output: Layer with functional role